


Features

- Provides ESD Protection per IEC 61000-4-2 Standard: Air ±30kV, Contact ±25kV
- 1 Channel of ESD Protection
- Ideal for 60V MOSFET Protection
- High Peak Pulse Current per IEC 61000-4-5 Standard
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

- Case: SOD323
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 
- Weight: 0.004 grams (approximate)

SOD323

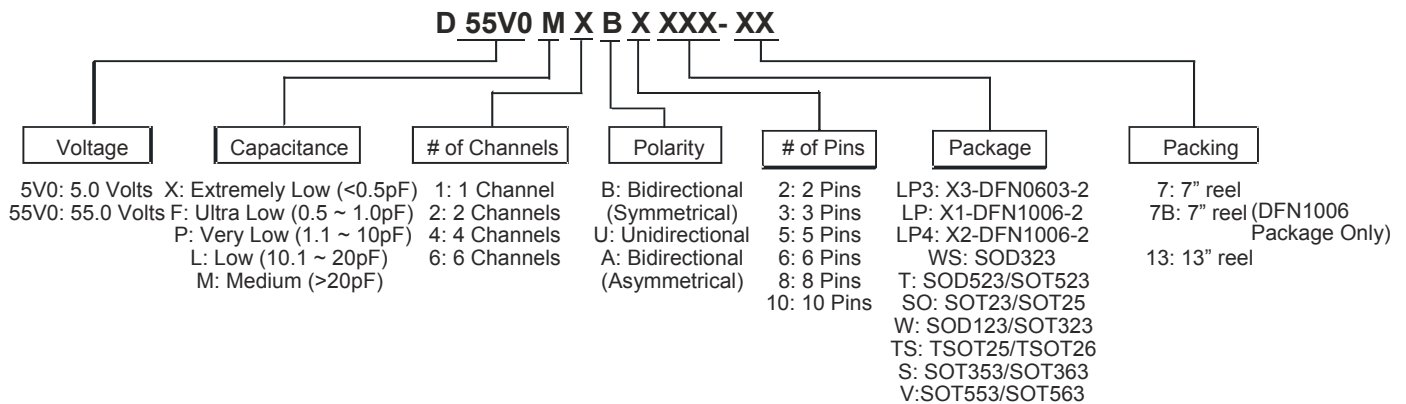


Bottom View



Device Schematic

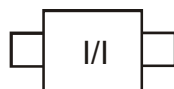
Ordering Information (Note 4)



Product	Compliance	Marking	Reel size(inches)	Tape width(mm)	Quantity per reel
D55V0M1B2WS-7	Standard	I/I	7	8	3,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



I/I = Product Type Marking Code

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P_{PP}	200	W	8/20 μs , Per Figure 2
Peak Pulse Current	I_{PP}	2	A	8/20 μs , Per Figure 2
ESD Protection – Contact Discharge	$V_{ESD_Contact}$	± 25	kV	IEC 61000-4-2 Standard
ESD Protection – Air Discharge	V_{ESD_Air}	± 30	kV	IEC 61000-4-2 Standard

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P_D	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	500	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Standoff Voltage	V_{RWM}	—	—	55	V	-
Channel Leakage Current (Note 6)	I_{RM}	—	—	100	nA	$V_{RWM} = 55\text{V}$
Clamping Voltage	V_{CL}	—	—	86 100	V	$I_{PP} = 1\text{A}, t_p = 8/20\mu\text{s}$ $I_{PP} = 2\text{A}, t_p = 8/20\mu\text{s}$
Breakdown Voltage	V_{BR}	57	—	—	V	$I_R = 1\text{mA}$
Channel Input Capacitance	C_T	—	14	25	pF	$V_R = 0\text{V}, f = 1\text{MHz}$

- Notes:
- Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.
 - Short duration pulse test used to minimize self-heating effect.

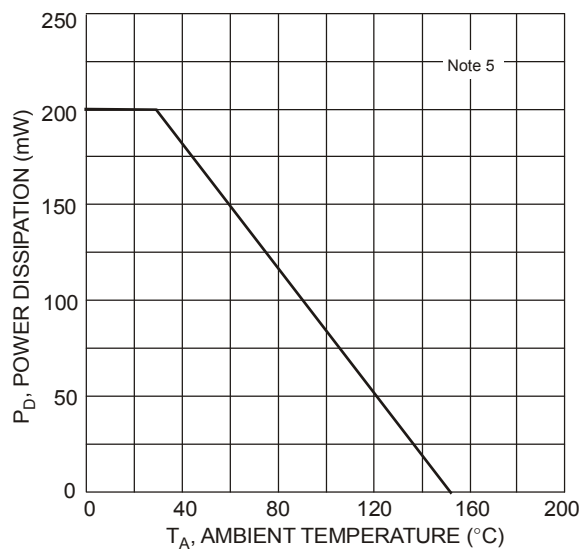


Figure 1 Power Derating Curve

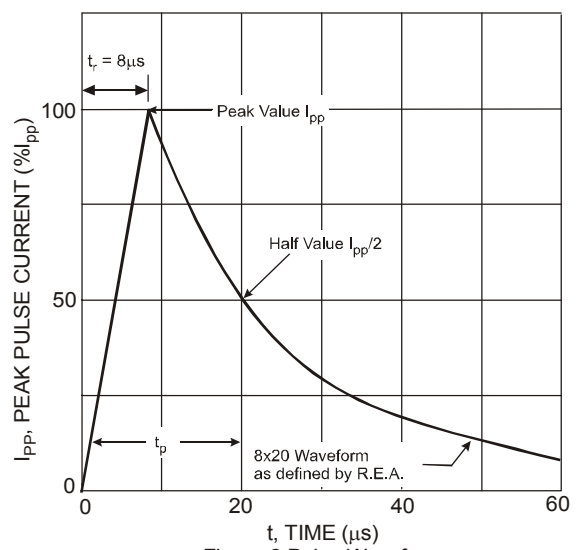


Figure 2 Pulse Waveform

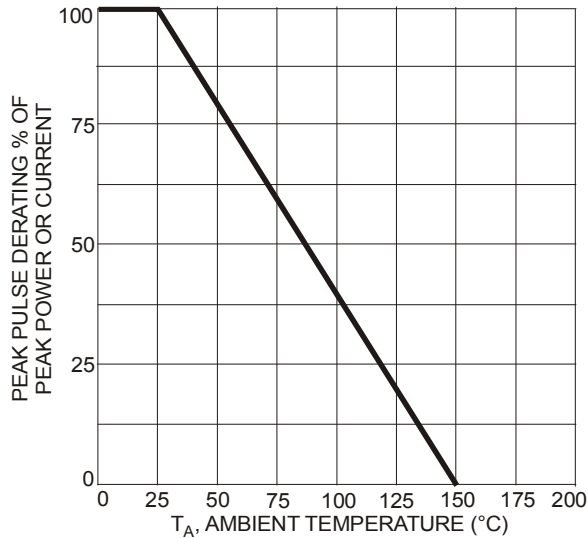


Figure 3 Power Dissipation vs. Ambient Temperature

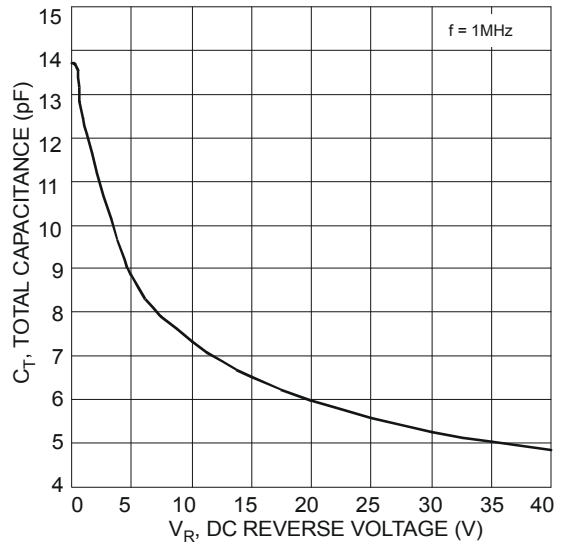


Figure 4 Total Capacitance vs. Reverse Voltage

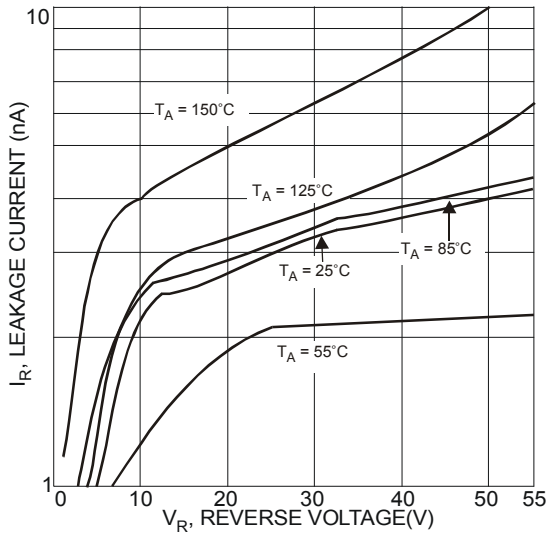
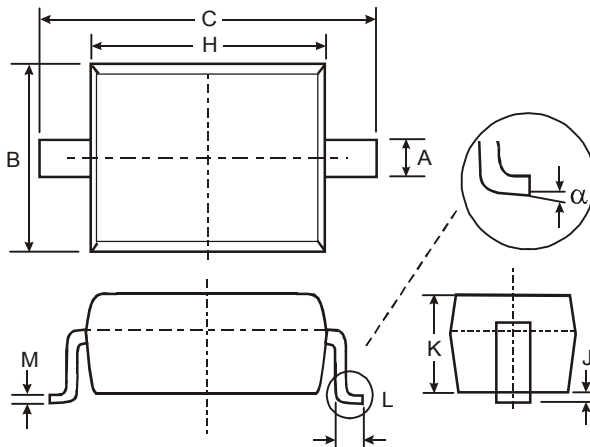


Figure 5 Typical Reverse Characteristics

Package Outline Dimensions

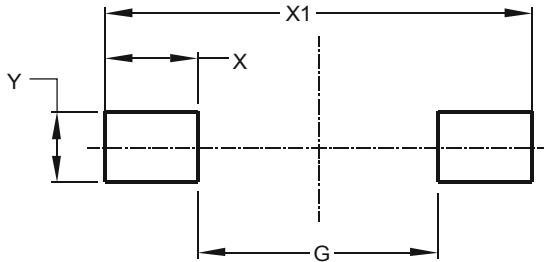
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOD323		
Dim	Min	Max
A	0.25	0.35
B	1.20	1.40
C	2.30	2.70
H	1.60	1.80
J	0.00	0.10
K	1.0	1.1
L	0.20	0.40
M	0.10	0.15
α	0°	8°
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
G	1.520
X	0.590
X1	2.700
Y	0.450

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